



Material Content Data Sheet



Sales Product Name				IPD048N06L3 G		Issued		25. September 2017	
MA#				MA000471034					
Package				PG-TO252-3-311		Weight*		315.12 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	1.08	1.08	10768	10768	
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		455		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	copper	7440-50-8	143.098	45.40	45.46	454109	454700	
wire	non noble metal	aluminium	7429-90-5	4.234	1.34	1.34	13435	13435	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.935	0.61		6141		
	plastics	brominated resin	-	2.073	0.66		6580		
	organic material	carbon black	1333-86-4	2.212	0.70		7018		
	plastics	epoxy resin	-	18.660	5.92		59216		
	inorganic material	silicondioxide	60676-86-0	113.342	35.97	43.86	359682	438637	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11869	11869	
plating	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	274	275	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
solder	noble metal	silver	7440-22-4	0.074	0.02		234		
	non noble metal	tin	7440-31-5	0.059	0.02		188		
	non noble metal	lead	7439-92-1	2.822	0.90	0.94	8957	9379	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.09	6.10	60858	60937	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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